

CLAIMS

1. A flip chip mounting substrate which comprises an electronic circuit composed of a circuit line and plural mounting pads connected to both ends of the circuit line formed on one surface of a base sheet, wherein the plural mounting pads are faced each other and spaced a pad clearance gap apart, and one or more semiconductor mounting paste guide paths are formed in the mounting pads.
2. The flip chip mounting substrate as claimed in claim 1, wherein a width of the semiconductor mounting paste guide path is in the range from 50 to 600 μm .
3. The flip chip mounting substrate as claimed in claim 1 or claim 2, wherein a broad section for pressing out and spreading uniformly the semiconductor mounting paste for connecting to an IC chip is formed in a part of the pad clearance gap.
4. The flip chip mounting substrate as claimed in claim 3, wherein a thin film layer is formed in center section of the broad section.